

EE-612: Lecture 25: SOI Electrostatics

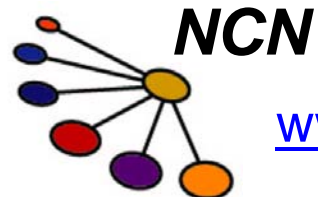
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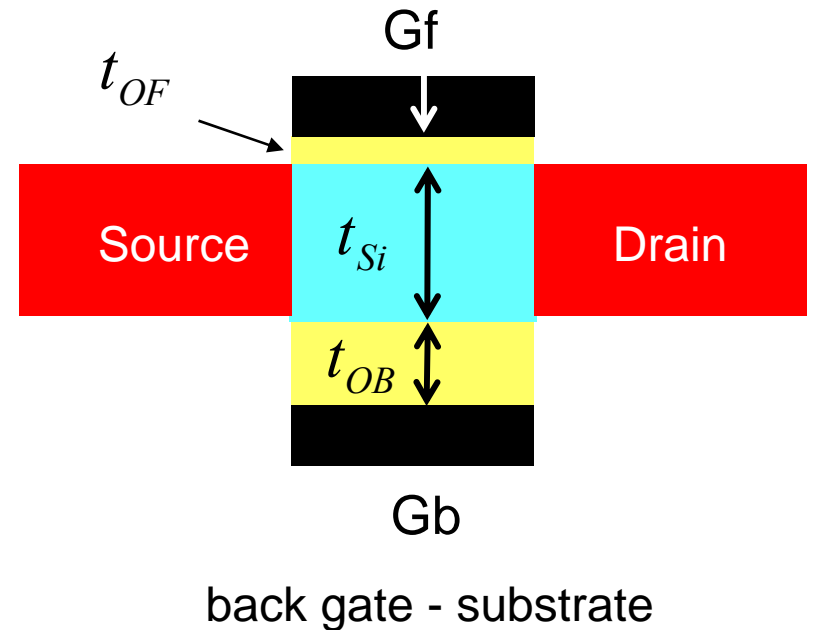
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outline

1. Introduction
2. General solution
3. V_{TF} vs. V_{GB}
4. Subthreshold slope
5. Double gate (DG) SOI
6. Recap
7. Discussion
8. Summary

SOI MOSFETs

- Two separate gates
- Upper oxide thermal
- Lower gate oxide is the BOX (e.g. produced by SIMOX)
- Typically $t_{OF} \ll t_{OB}$



Goal: To understand the effect of the top and back gates on MOSFET operation

band diagram: PD SOI

- Maximum depletion width for bulk Si:

$$W_{DM} = \sqrt{\frac{4\epsilon_{Si}\psi_B}{qN_A}} \quad \psi_B = \frac{k_B T}{q} \ln\left(\frac{N_A}{n_i}\right)$$

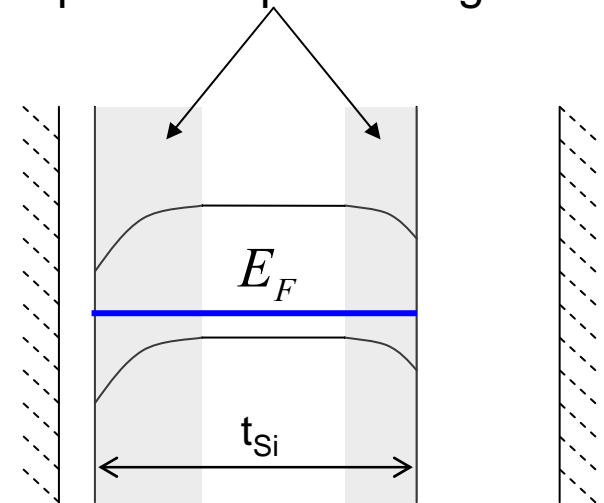
- Partially depleted (PD) SOI:

$$t_{Si} > 2W_{DM}$$

- Front and back gates are decoupled electrostatically: ψ_{SF} independent of ψ_{SB}

- Device operation similar to a bulk MOSFET

separate depletion regions

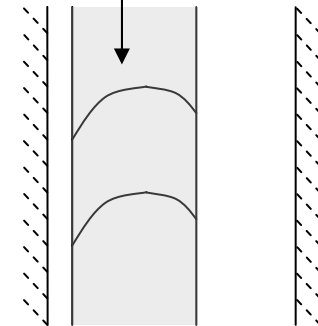


partially depleted
SOI film

band diagram: FD SOI

- Fully depleted (FD) SOI: $t_{Si} < W_{DM}$
- Front and back gates are electrostatically coupled: ψ_{SF} is a function of ψ_{SB}
- Back gate bias plays important role in device operation

Depletion regions merged



fully depleted
SOI film

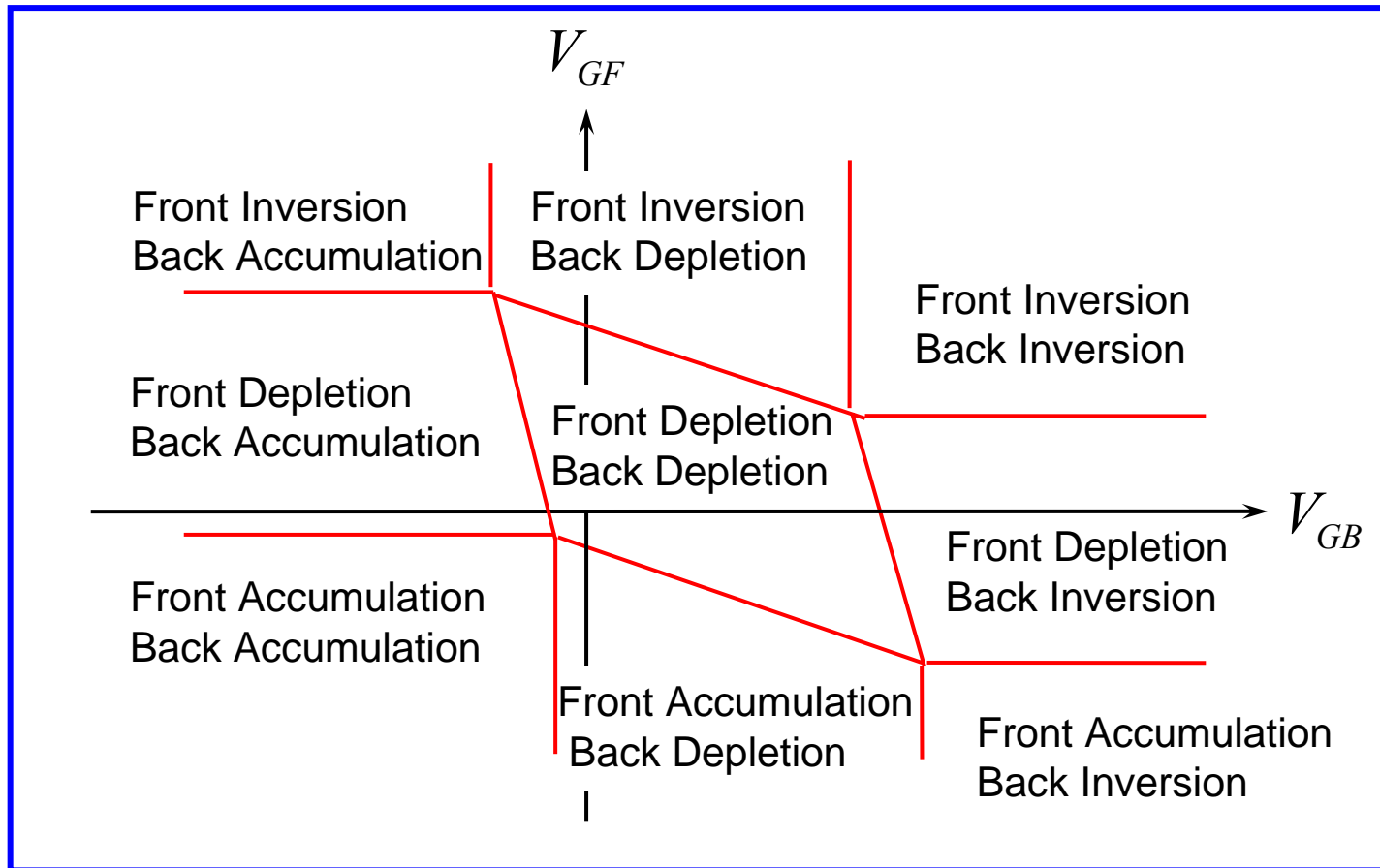
- The rest of this lecture will focus on fully depleted SOI

FD SOI nMOSFET operating regions

Nine operating regions:

Front gate:	Back gate:
depleted	depleted
inverted	inverted
accumulated	accumulated

FD SOI nMOSFET operating regions



Key references for SOI 1D Electrostatics

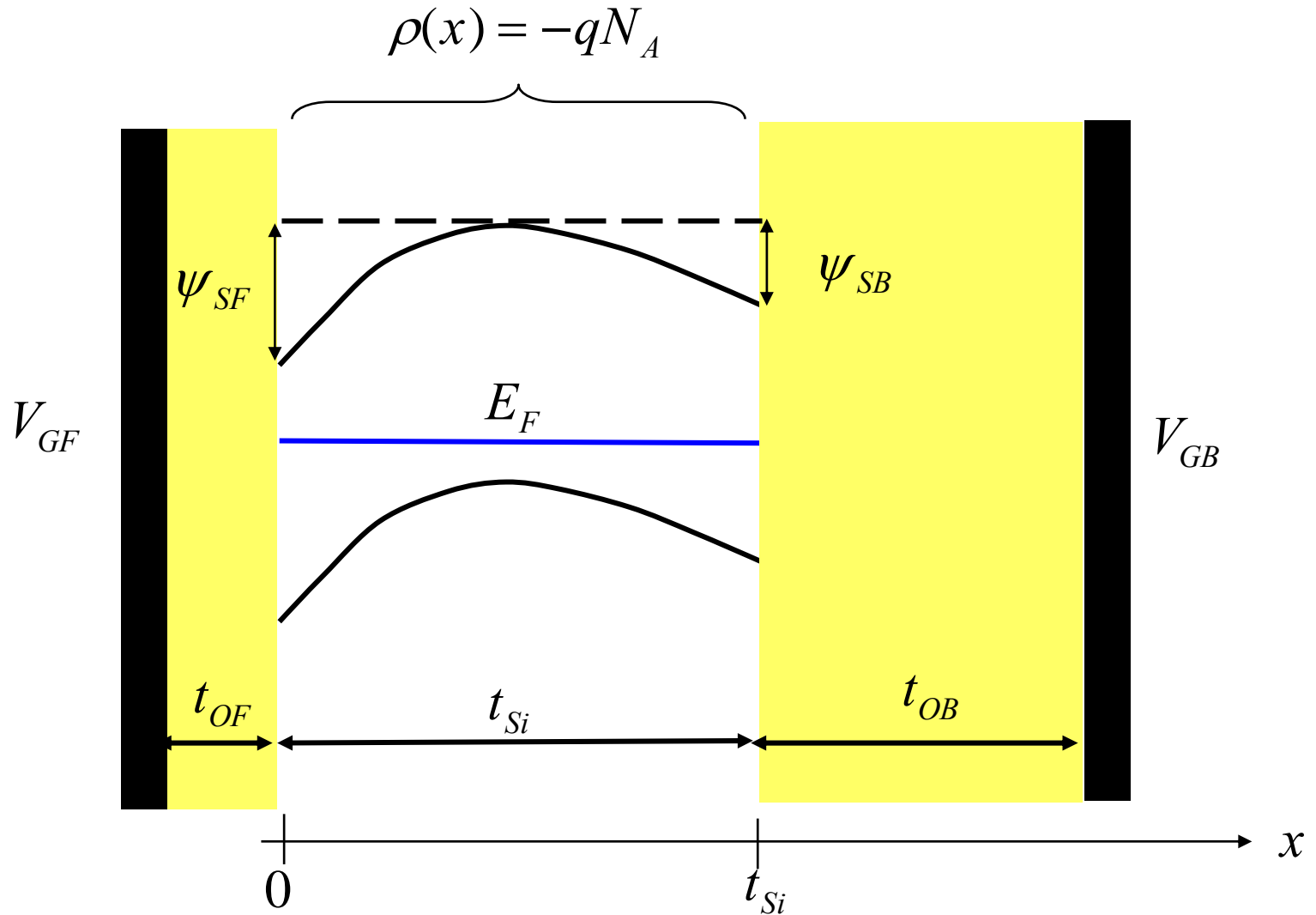
H.-K Lim and J.G. Fossum, "Threshold Voltage of Thin-Film Silicon-on-Insulator (SOI) MOSFETs," *IEEE Trans. Electron Devices*, **30**, 1244-1251, 1983.

V.P. Trivedi, J.G. Fossum, and W. Zhang, "Threshold Voltage in Nonclassical CMOS Devices with Undoped Ultra-Thin Bodies," *IEEE Trans. Electron Devices*, 2006.

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FD SOI band diagram



objectives

for bulk MOSFETS, we know:

$$V'_G = \psi_S - Q_S / C_{ox}$$

for FDSOI MOSFETS, determine:

$$\psi_{SF} = f(V_{GF}, V_{GB})$$

$$\psi_{SB} = f(V_{GF}, V_{GB})$$

electric field in SOI

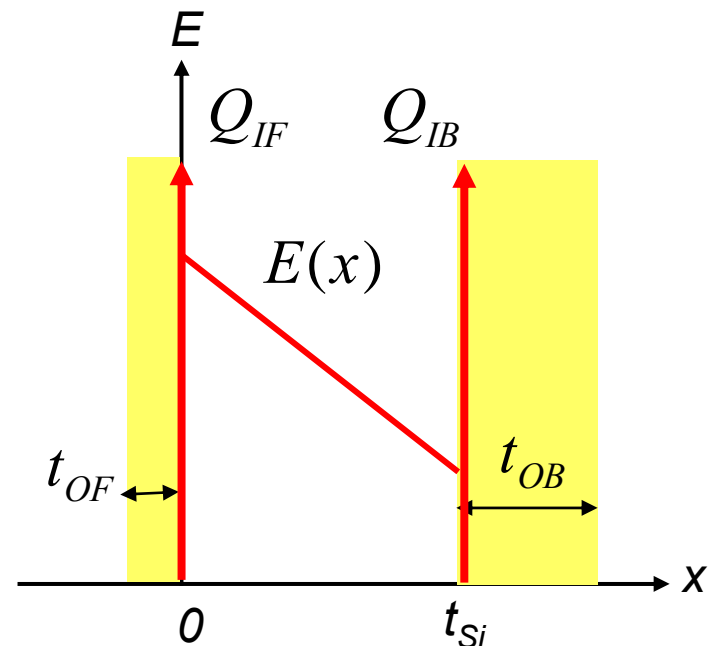
Delta-depletion Approximation: Assume that any mobile charge is at the Si surface in a delta function

Apply Gauss' Law to FD **bulk**:

$$\frac{dE}{dx} = \frac{-qN_A}{\epsilon_{Si}}$$

$$\int_{E(0^+)}^{E(t_{Si}^-)} dE = \frac{-qN_A}{\epsilon_{Si}} \int_{0^+}^{t_{Si}^-} dx$$

$$E(t_{Si}^-) - E(0^+) = -qN_A t_{Si} / \epsilon_{Si}$$



electric field in SOI (ii)

from:

$$E(t_{Si}^-) - E(0^+) = -qN_A t_{Si} / \epsilon_{Si}$$

we get:

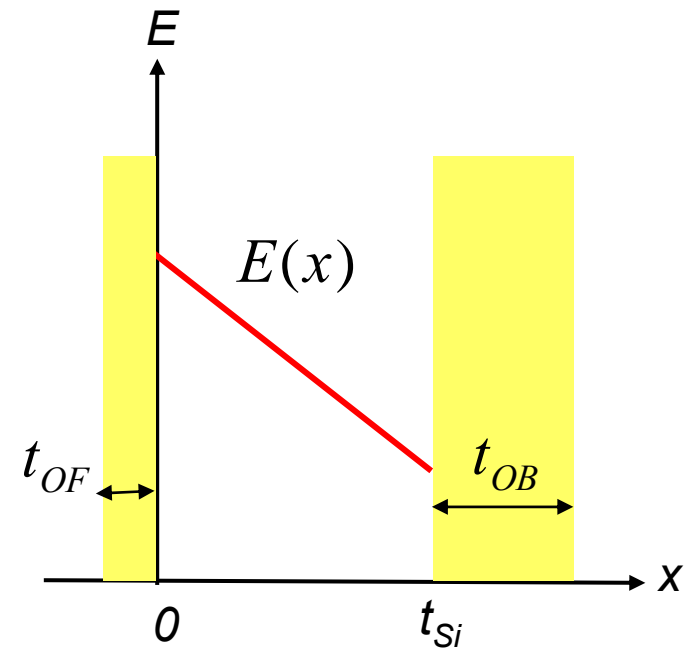
$$E(0^+) = E(t_{Si}^-) + qN_A t_{Si} / \epsilon_{Si} \quad (1)$$

also:

$$\Delta\psi = \psi_{SF} - \psi_{SB} = \frac{1}{2} [E(0^+) + E(t_{Si}^-)] t_{Si}$$

from which, we obtain:

$$E(0^+) = 2(\psi_{SF} - \psi_{SB}) / t_{Si} - E(t_{Si}^-) \quad (2)$$



electric field in SOI (iii)

solve (1) and (2) for:

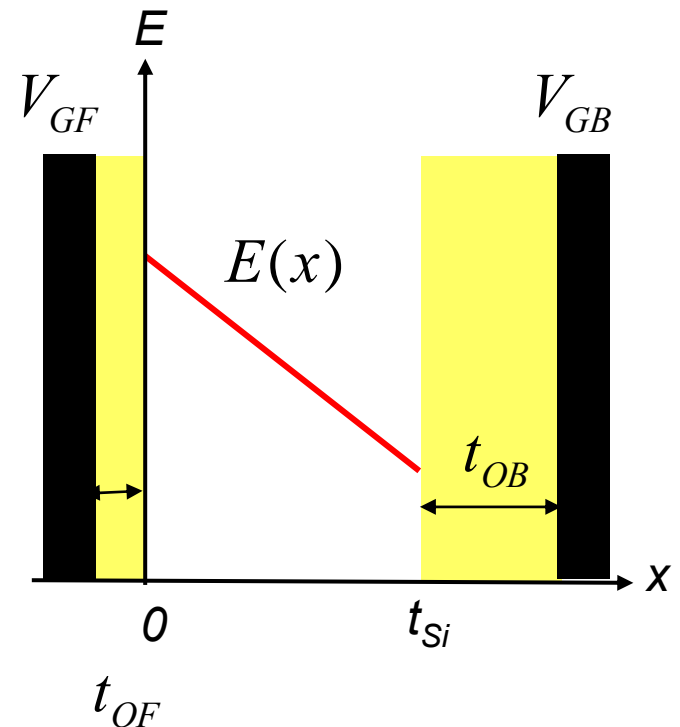
$$E(0^+) = \left(\frac{\psi_{SF} - \psi_{SB}}{t_{Si}} \right) + \frac{qN_A t_{Si}}{2\epsilon_{Si}} \quad (3)$$

$$E(t_{Si}^-) = \left(\frac{\psi_{SF} - \psi_{SB}}{t_{Si}} \right) - \frac{qN_A t_{Si}}{2\epsilon_{Si}} \quad (4)$$

we can also relate:

$$E(0^+) \text{ to } V_{GF}$$

$$E(t_{Si}^-) \text{ to } V_{GB}$$



effect of front and back gate voltages

The field in the front gate oxide is:

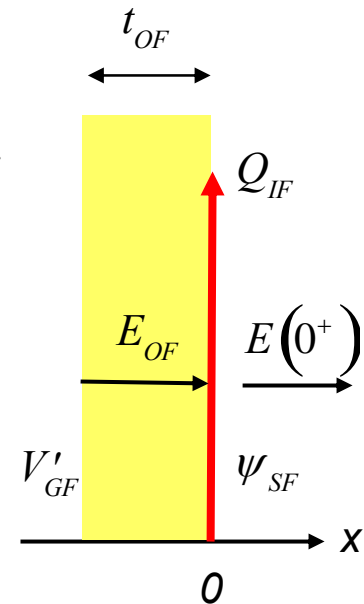
$$E_{OF} = (V'_{GF} - \psi_{SF}) / t_{OF}, \quad \text{where } V'_{GF} = V_{GF} - \phi_{msf}$$

Taking the inversion charge into account:

$$\epsilon_{ox} E_{OF} = \epsilon_{Si} E(0^+) - Q_{IF}$$

$$E(0^+) = \frac{\epsilon_{ox}}{\epsilon_{Si}} E_{OF} + \frac{Q_{IF}}{\epsilon_{Si}}$$

$$E(0^+) = \frac{\epsilon_{ox}}{\epsilon_{Si}} \frac{(V'_{GF} - \psi_{SF})}{t_{OF}} + \frac{Q_{IF}}{\epsilon_{Si}} \quad (5)$$



effect of front and back gate voltages (ii)

after a similar analysis for the back gate:

$$E(0^+) = \frac{\epsilon_{ox}}{\epsilon_{Si}} \frac{(V'_{GF} - \psi_{SF})}{t_{OF}} + \frac{Q_{IF}}{\epsilon_{Si}} \quad (5)$$

$$E(t_{Si}^-) = \frac{\epsilon_{ox}}{\epsilon_{Si}} \frac{(\psi_{SB} - V'_{GB})}{t_{OB}} - \frac{Q_{IB}}{\epsilon_{Si}} \quad (6)$$

$$E(0^+) = \left(\frac{\psi_{SF} - \psi_{SB}}{t_{Si}} \right) + \frac{qN_A t_{Si}}{2\epsilon_{Si}} \quad (3)$$

$$E(t_{Si}^-) = \left(\frac{\psi_{SF} - \psi_{SB}}{t_{Si}} \right) - \frac{qN_A t_{Si}}{2\epsilon_{Si}} \quad (4)$$

$$V_{GF}(\psi_{SF}, \psi_{SB})$$

$$V_{GB}(\psi_{SF}, \psi_{SB})$$

general solution

$$V_{GF} = \phi_{msf} + \psi_{SF} - \frac{Q_{IF} + Q_B/2}{C_{OF}} + \frac{C_{Si}}{C_{OF}} \times (\psi_{SF} - \psi_{SB}) \quad (7)$$

$$V_{GB} = \phi_{msb} + \psi_{SB} - \frac{Q_{IB} + Q_B/2}{C_{OB}} + \frac{C_{Si}}{C_{OB}} \times (\psi_{SB} - \psi_{SF}) \quad (8)$$

$$C_{Si} \equiv \frac{\epsilon_{Si}}{t_{Si}} \quad Q_B \equiv -qN_A t_{Si}$$

extra volt drop across oxide
due to different surface
potentials

compare to: $V'_G = \psi_S - Q_S/C_{ox}$

extra term due to different surface potentials

For bulk silicon MOS structure, the gate voltage is given by:

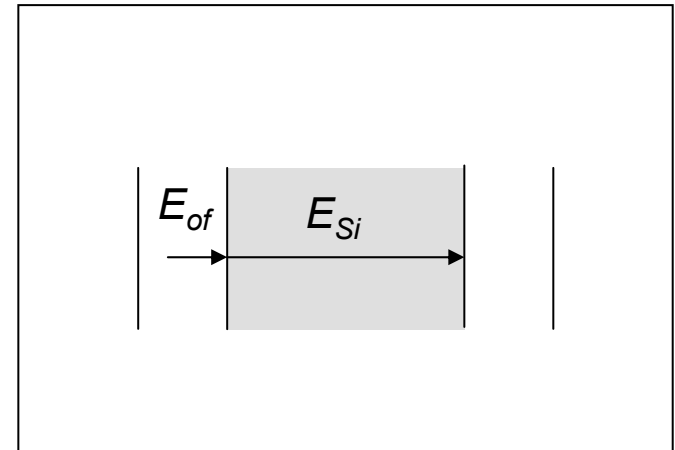
$$V_G = \psi_S - (Q_B + Q_I) / C_{ox}$$

Comparing with the bulk, the DGSOI gate voltage has an extra term that accounts for the voltage drop across oxide due to different surface potentials.

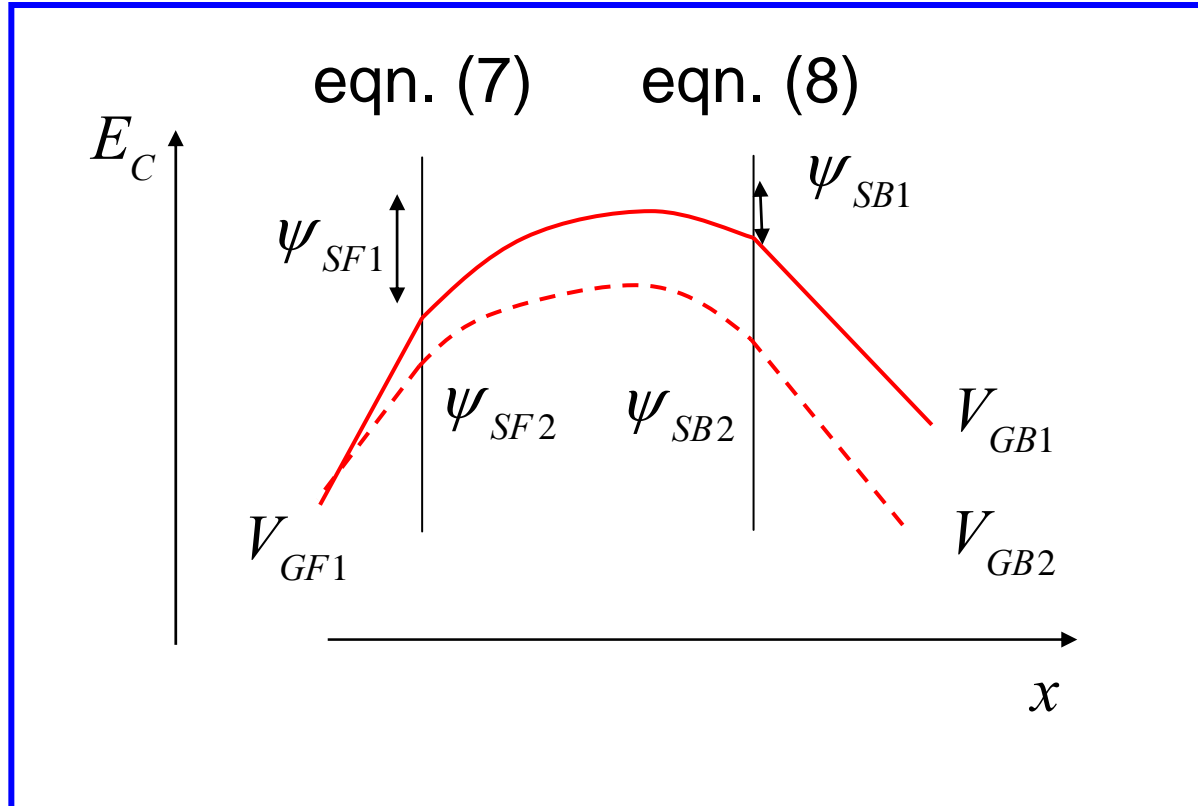
$$E_{Si} = (\psi_{SF} - \psi_{SB}) / t_{Si}$$

$$\epsilon_{of} E_{OF} = \epsilon_{Si} E_{Si} ? \quad \epsilon_{of} E_{OF} = \epsilon_{Si} (\psi_{SF} - \psi_{SB}) / t_{Si}$$

$$\Delta V_{OX} = t_{OF} E_{OF} = \frac{C_{Si}}{C_{OF}} (\psi_{SF} - \psi_{SB})$$



front and back coupled electrostatics

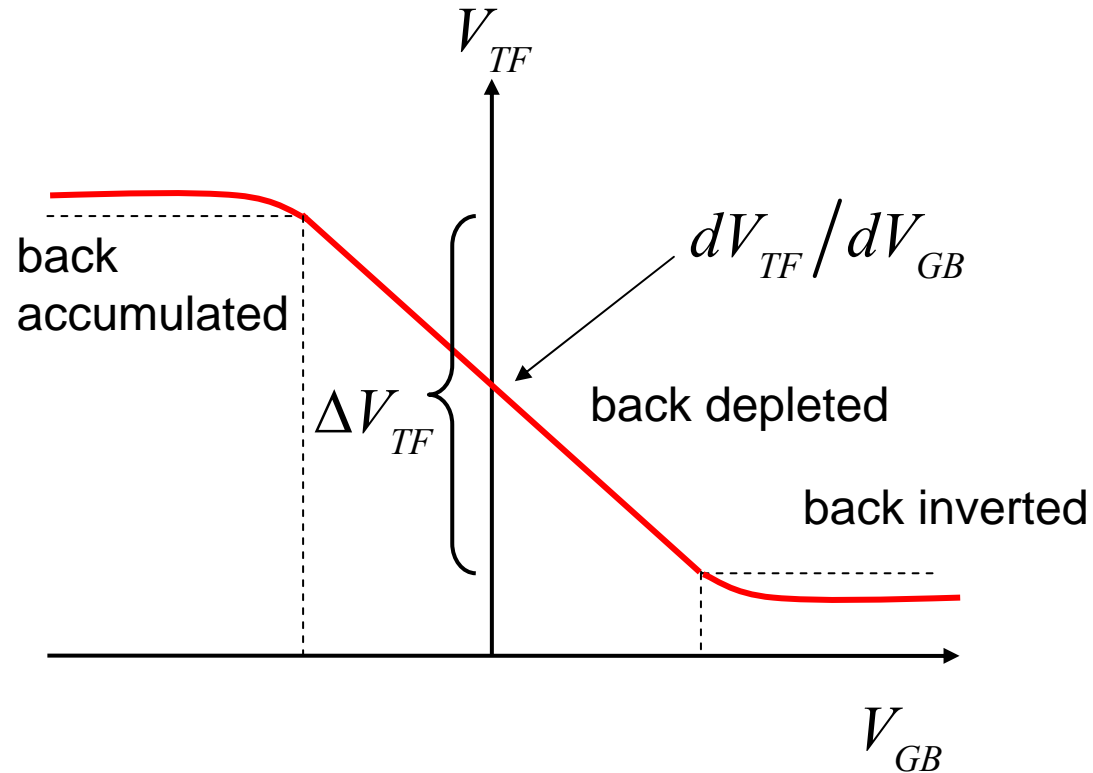


for a fixed V_{GF} , increasing V_{GB} increases ψ_{SF} (lowers V_{TF})

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V_{TF} vs. V_{GB}



threshold voltage (V_{TF})

Raising V_{GB} increases ψ_{SF} , so the front gate threshold voltage V_{TF} should **decrease**.

$$V_{GF} = \phi_{msf} + \psi_{SF} - \frac{Q_{IF} + Q_B/2}{C_{OF}} + \frac{C_{Si}}{C_{OF}} \times (\psi_{SF} - \psi_{SB})$$

At threshold, $Q_{IF} = Q_B/2$ and $\psi_{SF} = 2\psi_B$

$$V_{TF} = \phi_{msf} + 2\psi_B - \frac{Q_B}{2C_{OF}} + \frac{C_{Si}}{C_{OF}} (2\psi_B - \psi_{SB})$$

V_{TF} is a function of ψ_{SB} , and hence can be varied using back gate bias (V_{GB})

1) back inverted

$$V_{TF} = \phi_{msf} + 2\psi_B - \frac{Q_B}{2C_{OF}} + \frac{C_{Si}}{C_{OF}} (2\psi_B - \psi_{SB})$$

Back side inversion:

$$\psi_{SB} = 2\psi_B$$

$$V_{TF} (\text{back inv}) = \phi_{msf} + 2\psi_B - \frac{Q_B}{2C_{OF}}$$

Current flows even when $V_{GF} < V_{TF}$ because the back surface is inverted. Since the device doesn't turn off, this mode of operation is not useful.

2) back accumulated

$$V_{TF} = \phi_{msf} + 2\psi_B - \frac{Q_B}{2C_{OF}} + \frac{C_{Si}}{C_{OF}} (2\psi_B - \psi_{SB})$$

Back accumulation:

$$\psi_{SB} \approx 0$$

$$V_{TF} (\text{back acc}) = \phi_{msf} + 2\psi_B - \frac{Q_B}{2C_{OF}} + \frac{C_{Si}}{C_{OF}} (2\psi_B)$$

Net V_{TF} shift:

$$\begin{aligned} \Delta V_{TF} &= V_{TF} (\text{back acc}) - V_{TF} (\text{back inv}) \\ &= \frac{C_{Si}}{C_{OF}} (2\psi_B) = \frac{\epsilon_{Si}}{\epsilon_{ox}} \frac{t_{OF}}{t_{Si}} (2\psi_B) \end{aligned}$$

3) back depleted

$$V_{GF} = \phi_{msf} + \psi_{SF} - \frac{Q_{IF} + Q_B/2}{C_{OF}} + \frac{C_{Si}}{C_{OF}} \times (\psi_{SF} - \psi_{SB}) \quad (7)$$

$$V_{TF} = \phi_{msf} + 2\psi_{SB} - \frac{Q_B}{2C_{OF}} + \frac{C_{Si}}{C_{OF}} \times (2\psi_B - \psi_{SB}) \quad (9)$$

We need to relate ψ_{SB} to $V_{GB} \dots$

3) back depleted (ii)

$$V_{GB} = \phi_{msb} + \psi_{SB} - \frac{Q_{IB} + Q_B/2}{C_{OB}} + \frac{C_{Si}}{C_{OB}} \times (\psi_{SB} - \psi_{SF}) \quad (8)$$

at front threshold:

$$V_{GB} = \phi_{msb} + \psi_{SB} - \frac{Q_B}{2C_{OB}} + \frac{C_{Si}}{C_{OB}} \times (\psi_{SB} - 2\psi_B) \quad (10)$$

at the start of back accumulation ($\psi_{SB} = 0$):

$$V_{GB}(\text{acc}) = \phi_{msb} - \frac{Q_B}{2C_{OB}} - \frac{C_{Si}}{C_{OB}} 2\psi_B \quad (11)$$

3) back depleted (iii)

The back surface is depleted when $V_{GB} > V_{GB}(\text{acc})$

From (10) and (11):

$$V_{GB} - V_{GB}(\text{acc}) = \left(1 + \frac{C_{Si}}{C_{OB}} \right) \psi_{SB}$$

$$\psi_{SB} = \frac{C_{ob}}{C_{OB} + C_{Si}} \left[V_{GB} - V_{GB}(\text{acc}) \right] \quad (12)$$

3) back depleted (iv)

recap:

$$V_{TF} = \phi_{msf} + 2\psi_{SB} - \frac{Q_B}{2C_{OF}} + \frac{C_{Si}}{C_{OF}} \times (2\psi_B - \psi_{SB}) \quad (9)$$

$$\psi_{SB} = \frac{C_{ob}}{C_{OB} + C_{Si}} [V_{GB} - V_{GB}(\text{acc})] \quad (12)$$

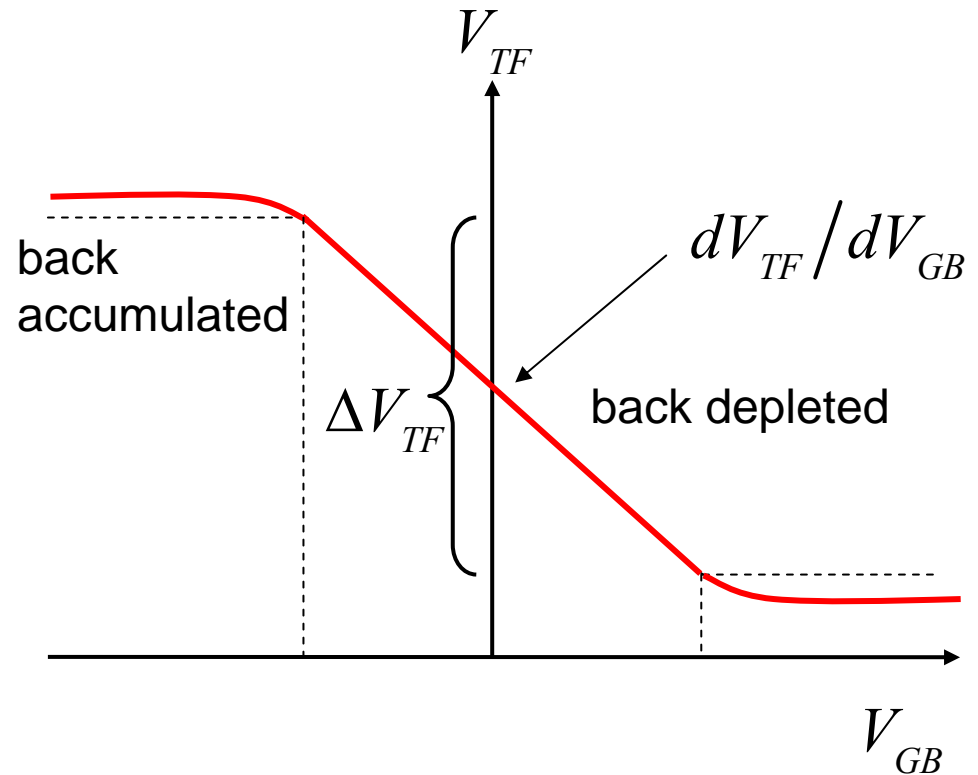
$$V_{TF} = \phi_{msf} + 2\psi_B - \frac{Q_B}{2C_{OF}} + \frac{C_{Si}}{C_{OF}} 2\psi_B - \frac{C_{Si}C_{OB}}{C_{OF}(C_{OB} + C_{Si})} [V_{GB} - V_{GB}(\text{acc})]$$

$$\frac{dV_{TF}}{dV_{GB}} = - \frac{C_{Si}C_{OB}}{C_{OF}(C_{OB} + C_{Si})} = - \left(\frac{t_{OF}}{t_{OB}} \right) \frac{1}{(1 + C_{OB}/C_{Si})}$$

V_T summary

$$\Delta V_{TF} = \frac{\epsilon_{Si} t_{OF}}{\epsilon_{ox} t_{Si}} (2\psi_B)$$

$$\frac{dV_{TF}}{dV_{GB}} = - \frac{t_{OF}/t_{OB}}{1 + C_{OB}/C_{Si}}$$



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subthreshold swing (bulk MOSFET review)

subthreshold current:

$$I_D \sim e^{q\psi_S/k_B T}$$

$$\ln I_D = q\psi_S / k_B T$$

$$2.303 \log I_D = q\psi_S / k_B T$$

subthreshold slope:

$$\frac{\partial \log I_D}{\partial V_{GS}} = \frac{1}{2.3(k_B T / q)} \frac{\partial \psi_S}{\partial V_{GS}} = S^{-1}$$

subthreshold swing:

$$S = 2.3(k_B T / q) \left(\frac{\partial \psi_S}{\partial V_{GS}} \right)^{-1} = 2.3m(k_B T / q)$$

$$m = \left(\frac{\partial \psi_S}{\partial V_{GS}} \right)^{-1}$$

subthreshold swing (SOI MOSFET)

subthreshold current: $I_D \sim e^{q\psi_{SF}/k_B T}$

subthreshold swing: $S = 2.3(k_B T / q) \left(\frac{\partial \psi_{SF}}{\partial V_{GF}} \right)^{-1} = 2.3m(k_B T / q)$

'body effect parameter': $m = \left(\partial \psi_{SF} / \partial V_{GF} \right)^{-1}$

SOI subthreshold swing derivation

return to general solution:

$$V_{GF} = \phi_{msf} + \psi_{SF} - \frac{Q_{IF} + Q_B/2}{C_{OF}} + \frac{C_{Si}}{C_{OF}} \times (\psi_{SF} - \psi_{SB}) \quad (7)$$

$$V_{GB} = \phi_{msb} + \psi_{SB} - \frac{Q_{IB} + Q_B/2}{C_{OB}} + \frac{C_{Si}}{C_{OB}} \times (\psi_{SB} - \psi_{SF}) \quad (8)$$

compute $dV_{GF} / d\psi_{SF}$ from (7)

assume Q_B is constant (FD)

SOI subthreshold swing derivation (ii)

$$\frac{\partial V_{GF}}{\partial \psi_{SF}} = 1 + \frac{C_{Si}}{C_{OF}} \left(1 - \frac{\partial \psi_{SB}}{\partial \psi_{SF}} \right) \quad (\odot)$$

To get $\frac{\partial \psi_{SB}}{\partial \psi_{SF}}$, differentiate (8) assuming V_{GB} is constant

$$0 = \frac{\partial \psi_{SB}}{\partial \psi_{SF}} + \frac{C_{Si}}{C_{OB}} \left(\frac{\partial \psi_{SB}}{\partial \psi_{SF}} - 1 \right)$$

$$\frac{\partial \psi_{SB}}{\partial \psi_{SF}} = \frac{C_{Si}/C_{OB}}{1 + C_{Si}/C_{OB}} = \frac{C_{Si}}{C_{Si} + C_{OB}} \quad \text{insert in } (\odot)$$

SOI subthreshold swing derivation (iii)

$$\frac{dV_{GF}}{d\psi_{SF}} = m = 1 + \frac{C_{Si}C_{OB}}{C_{OF}(C_{Si} + C_{OB})} \quad \left(m = 1 + \frac{C_D}{C_{ox}} \quad \text{bulk} \right)$$

$$C_D(\text{eff}) = \frac{C_{Si}C_{OB}}{(C_{Si} + C_{OB})} \quad m = 1 + \frac{C_D(\text{eff})}{C_{OF}}$$

if the bottom oxide is thick, $C_{OB} \ll C_{Si}, C_{OF}$ $m \rightarrow 1$

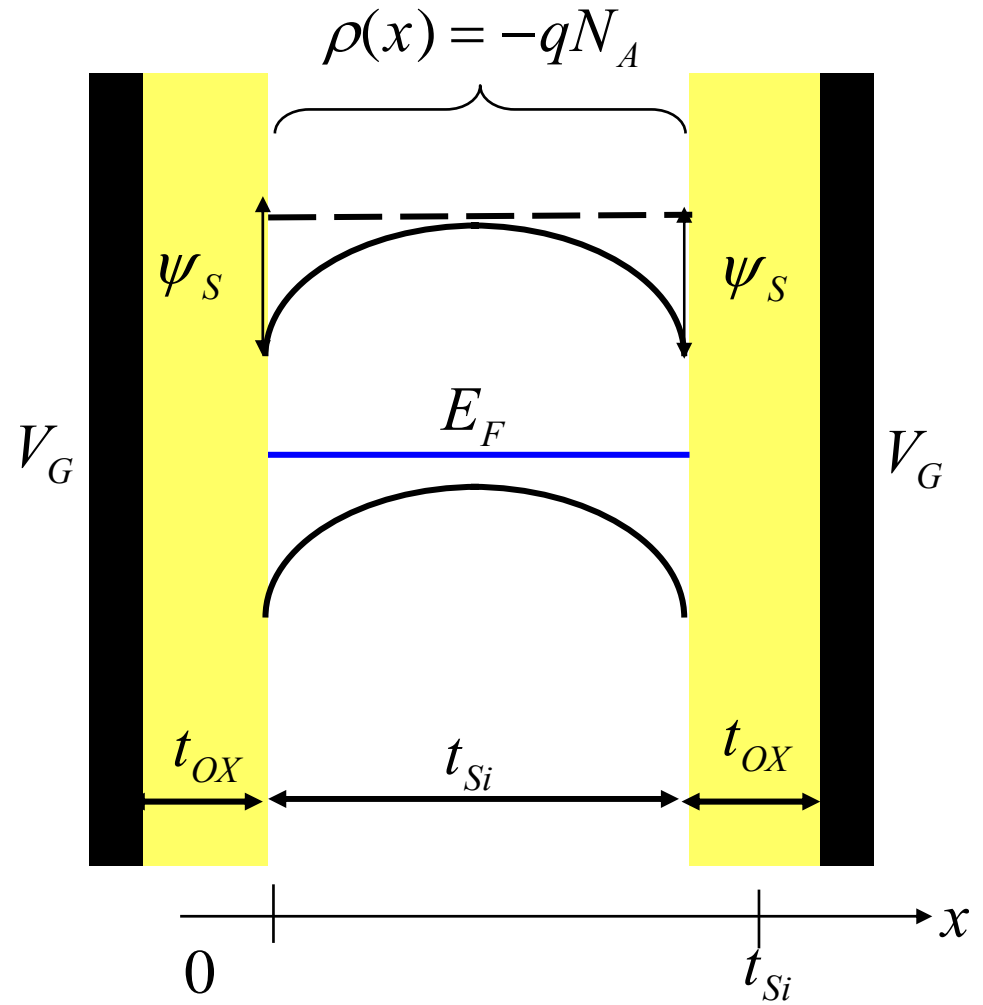
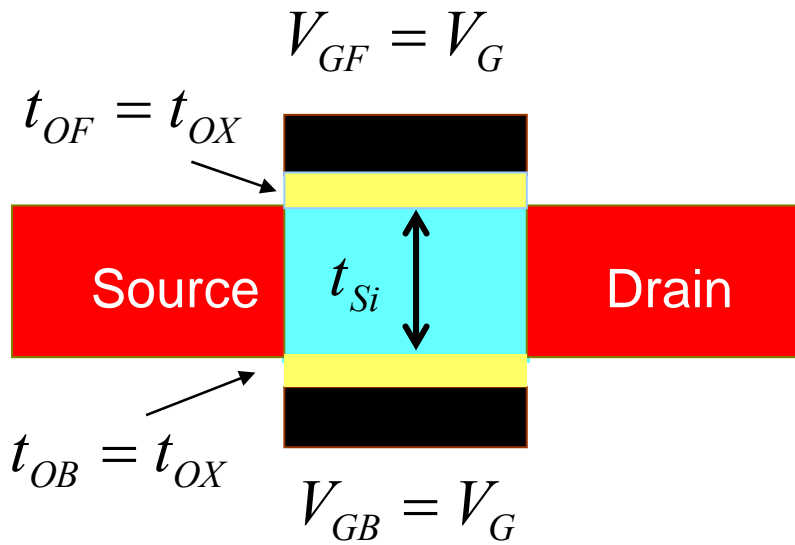
SOI summary

- 1) front and back gates are coupled electrostatically
- 2) front threshold voltage can be tuned by the back gate
- 3) for a thick BOX, the subthreshold swing is nearly ideal

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symmetrical double gate



DG electrostatics

$$V_{GF} = \phi_{msf} + \psi_{SF} - \frac{Q_{IF} + Q_B/2}{C_{OF}} + \frac{C_{Si}}{C_{OF}} \times (\psi_{SF} - \psi_{SB}) \quad (7)$$

$$V_{GB} = \phi_{msb} + \psi_{SB} - \frac{Q_{IB} + Q_B/2}{C_{OB}} + \frac{C_{Si}}{C_{OB}} \times (\psi_{SB} - \psi_{SF}) \quad (8)$$

for double gate SOI: $V_{GF} = V_{GB}$ $\psi_{SF} = \psi_{SB}$
 $C_{OF} = C_{OB} = C_{ox}$ $Q_{IF} = Q_{IB} = Q_I/2$

then either (7) or (8) gives:

$$V_G = \phi_{ms} + \psi_S - \frac{Q_I + Q_B}{2C_{ox}}$$

DG subthreshold swing

$$V_G = \phi_{ms} + \psi_S - \frac{Q_I + Q_B}{2C_{ox}} \quad Q_I \approx 0$$

$$\frac{dV_G}{d\psi_S} = m = 1 \quad (\text{fully depleted, } Q_B \text{ independent of } \psi_S)$$

ideal subthreshold characteristics

DG above threshold

$$V_G = \phi_{ms} + \psi_S - \frac{Q_B}{2C_{ox}} - \frac{Q_I}{2C_{ox}}$$

$$V_T = \phi_{ms} + 2\psi_B - \frac{Q_B}{2C_{ox}}$$

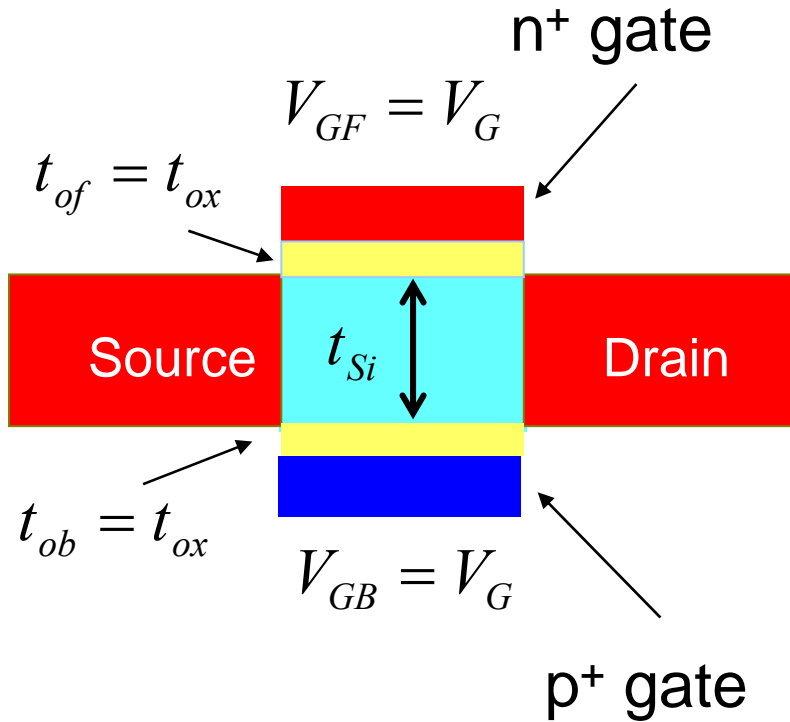
for $V_G > V_T$:

$$V_G - V_T = -\frac{Q_I}{2C_{ox}}$$

$$Q_I = -2C_{ox}(V_G - V_T)$$

twice as much charge \Rightarrow twice as much current

asymmetric gates



$$V_{GF} = V_{GB} = V_G$$

$$t_{OF} = t_{OB} = t_{OX}$$

$$\phi_{msf} \neq \phi_{msb}$$

how should

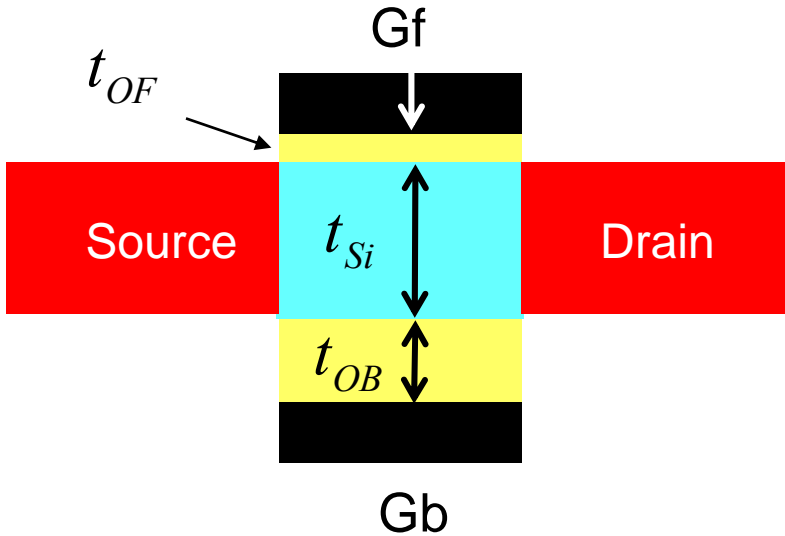
$$Q_I = -2C_{ox} (V_G - V_T)$$

be modified?

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review: SOI MOSFET general solution



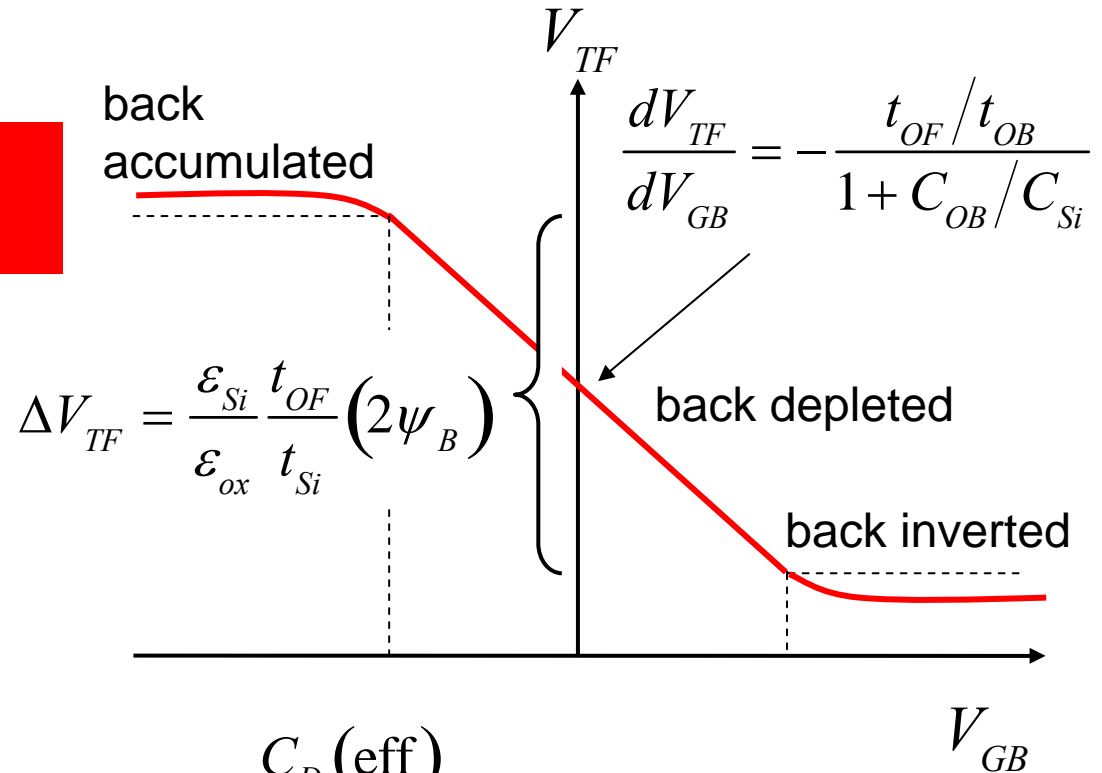
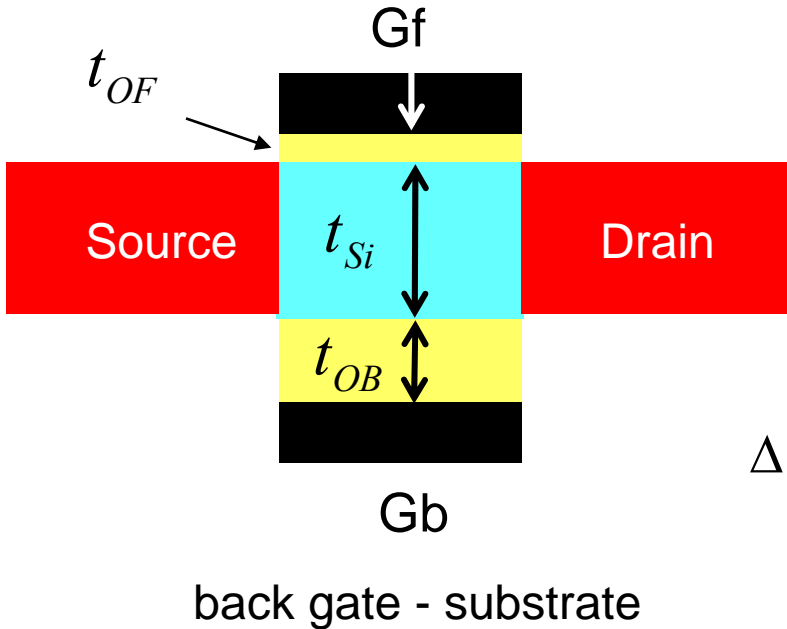
$$C_{Si} \equiv \frac{\epsilon_{Si}}{t_{Si}} \quad Q_B \equiv -qN_A t_{Si}$$

back gate - substrate

$$V_{GF} = \phi_{msf} + \psi_{SF} - \frac{Q_{IF} + Q_B/2}{C_{OF}} + \frac{C_{Si}}{C_{OF}} \times (\psi_{SF} - \psi_{SB}) \quad (7)$$

$$V_{GB} = \phi_{msb} + \psi_{SB} - \frac{Q_{IB} + Q_B/2}{C_{OB}} + \frac{C_{Si}}{C_{OB}} \times (\psi_{SB} - \psi_{SF}) \quad (8)$$

review: SOI MOSFETs key results

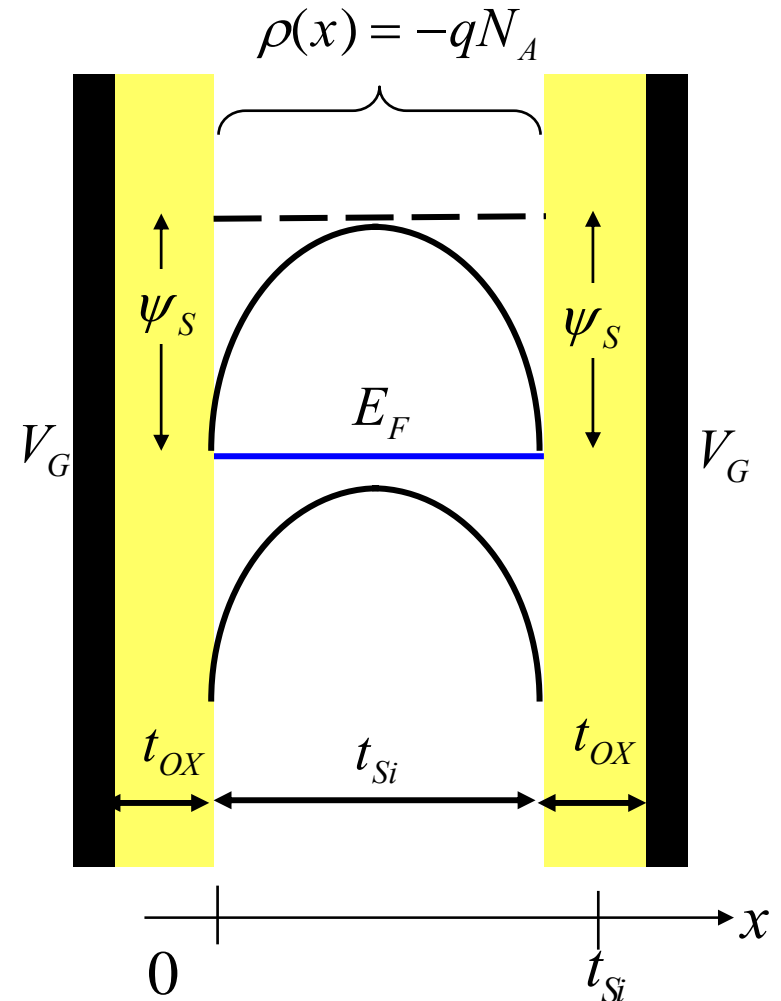
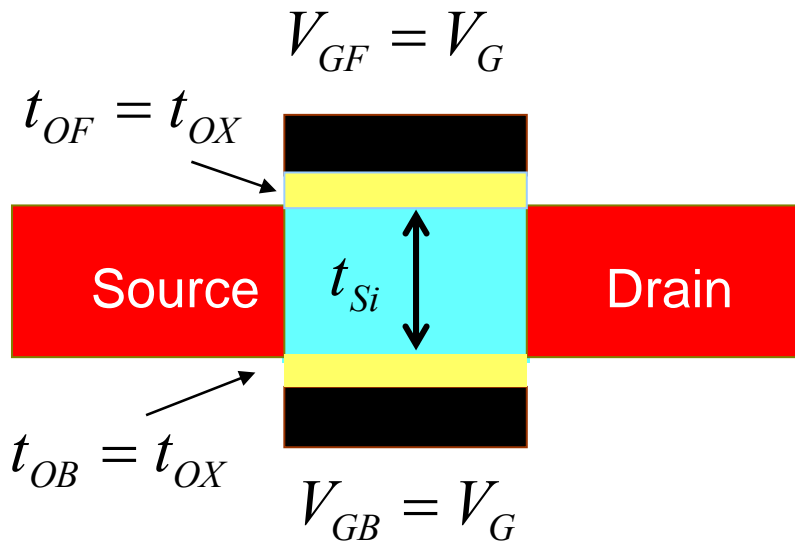


$$S = 2.3m(k_B T/q)$$

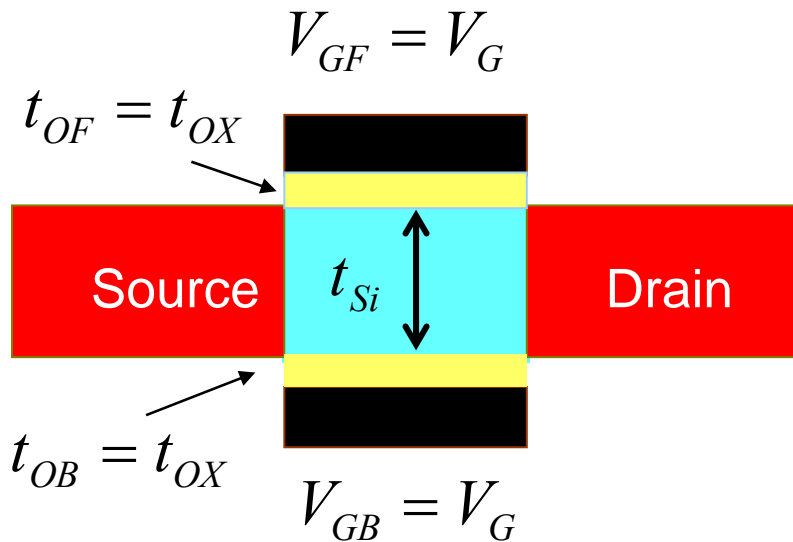
$$m = 1 + \frac{C_D(\text{eff})}{C_{OF}}$$

$$C_D(\text{eff}) = \frac{C_{Si} C_{OB}}{(C_{Si} + C_{OB})}$$

symmetrical double gate (SDG)



symmetrical double gate: key results



$$V_G = \phi_{ms} + \psi_S - \frac{Q_I + Q_B}{2C_{ox}}$$

$$V_T = \phi_{ms} + 2\psi_B - \frac{Q_B}{2C_{ox}}$$

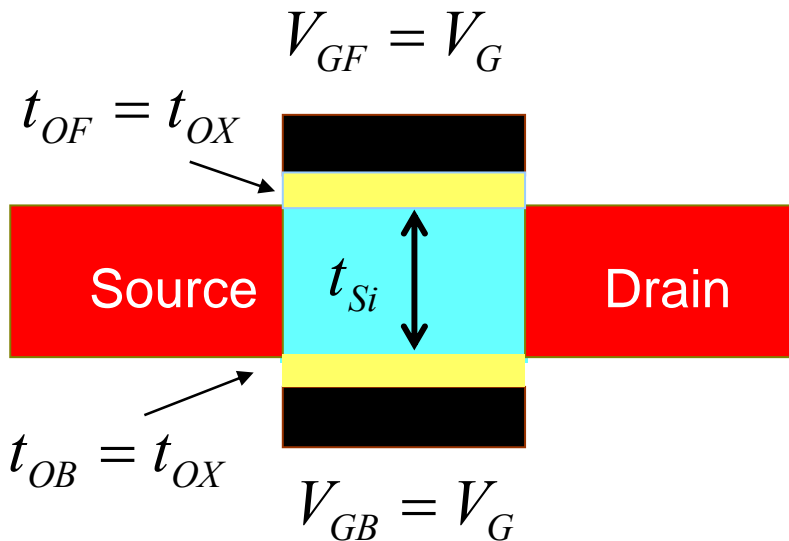
$$Q_I = -2C_{ox}(V_G - V_T)$$

$$S = 2.3(k_B T / q) \quad (\text{ideal})$$

ultra-thin body (UTB) DG MOSFET

If T_{Si} is very thin, then the device is called an ultra-thin-body SOI MOSFET

why UTB DG MOSFETs?



- good 2D electrostatics

$$\Lambda_{DG\ SOI} \approx \sqrt{\epsilon_{Si} t_{Si} t_{OX} / 2 \epsilon_{OX}} = \Lambda_{BULK} / \sqrt{2}$$

- undoped body

(no random dopant fluctuations of V_T)

- ideal subthreshold swing

issues:

V_T must be tuned with workfunctions

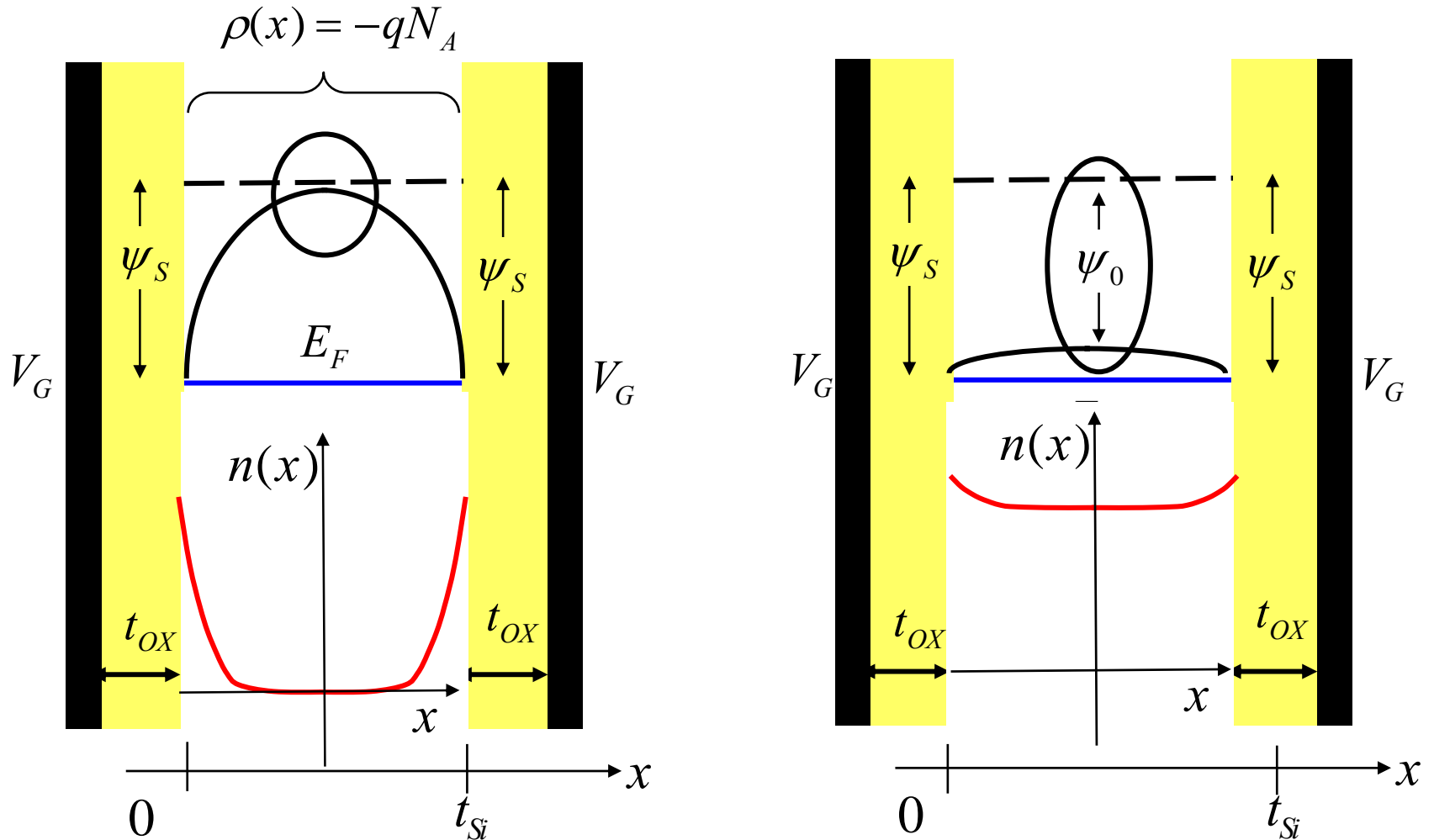
$2\psi_B$ loses relevance

mobility degradation for very thin bodies

outline

1. Introduction
2. General solution
3. V_{TF} vs. V_{GB}
4. Subthreshold slope
5. Double gate (DG) SOI
6. Recap
7. **Discussion**
8. Summary

thick vs. thin body



definition of UTB

1) fully depleted

$$t_{Si} < W_{DM} \quad \frac{dE}{dx} = \frac{-qN_A}{\epsilon_{Si}}$$

2) little band bending across the body

$$\Delta\psi < k_B T / q$$

(requires a numerical solution in general)

numerical (Schred) simulation

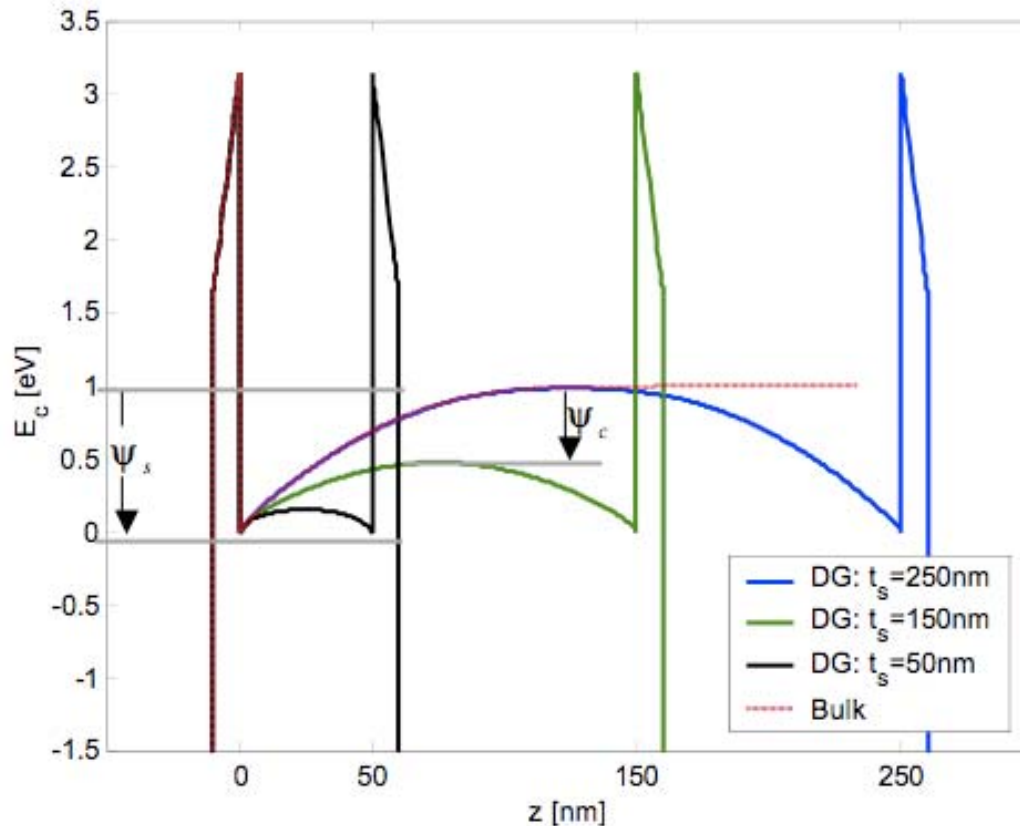


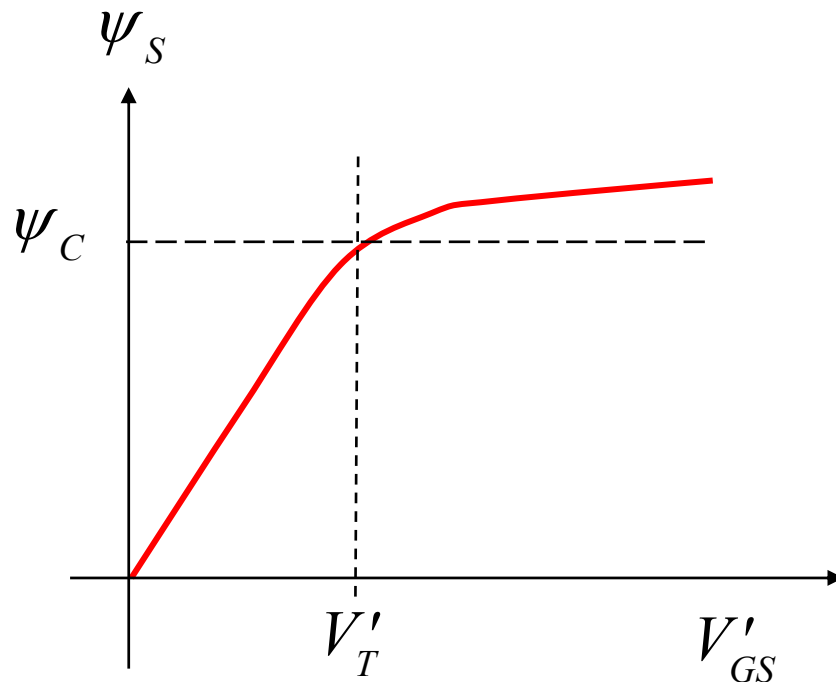
Fig. 14. Band-diagram of DG MOS capacitors of different body thickness at same V_G . Also shown the band diagram of bulk MOSC (red-dashed line). $t_{ox} = 10\text{nm}$, $N_A = 1.E17\text{ cm}^{-3}$, $V_G = 1.5\text{v}$. Classical mode calculation.

threshold voltage for an undoped body

$$V_G = \phi_{ms} + \psi_S$$

how to specify ψ_S ?

$$\psi_S \neq 2\psi_B$$



$$\psi_S < \psi_C$$

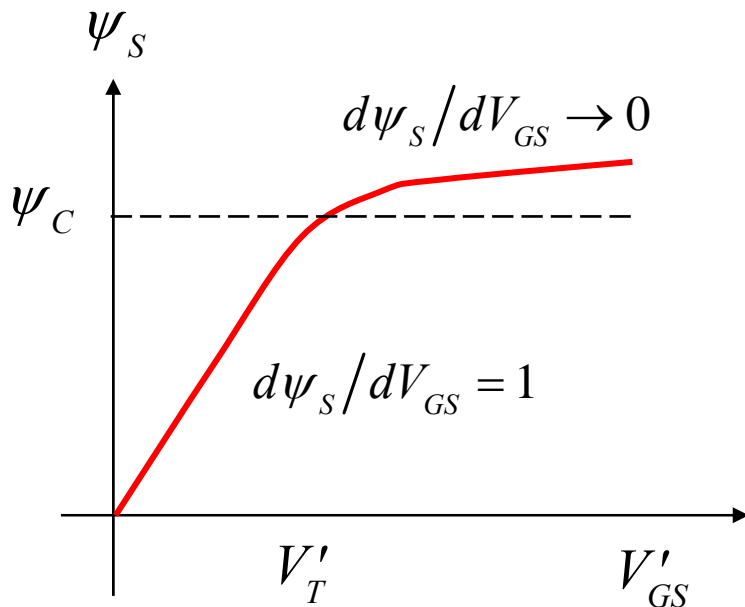
$$\frac{d\psi_S}{dV_{GS}} \approx 1$$

$$\psi_S > \psi_C$$

$$\frac{d\psi_S}{dV_{GS}} \rightarrow 0$$

threshold voltage (ii)

how to specify ψ_C ?



1) according to Trivedi, Fossum, and Zhang:

$$n_i e^{q\psi_C/k_B T} t_{Si} \approx 10^{11} \text{ cm}^2$$

2) also could say:

$$\psi_C = E_G/2q$$

3) another possibility:

$$d\psi_S/dV'_{GS} \Big|_{\psi=\psi_C} = 1/2$$

$$\psi_C = (k_B T/q) \ln(2C_{ox} k_B T/n_i t_{Si} q^2)$$

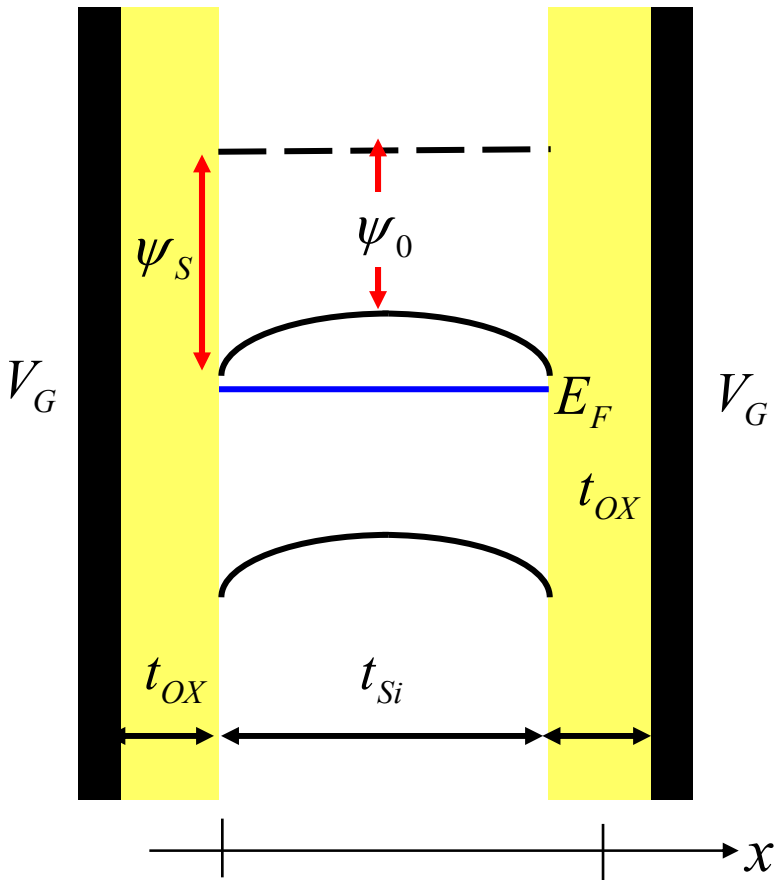
threshold voltage (iii)

$$V_G = \phi_{ms} + \psi_S - \frac{Q_I}{2C_{ox}}$$

$$V_T = \phi_{ms} + \psi_C$$

$$Q_I = -2C_{ox} (V_G - V_T)$$

UTB electrostatics above threshold



1) below threshold:

-bands are flat

2) weak / moderate inversion:

-bands are nearly flat

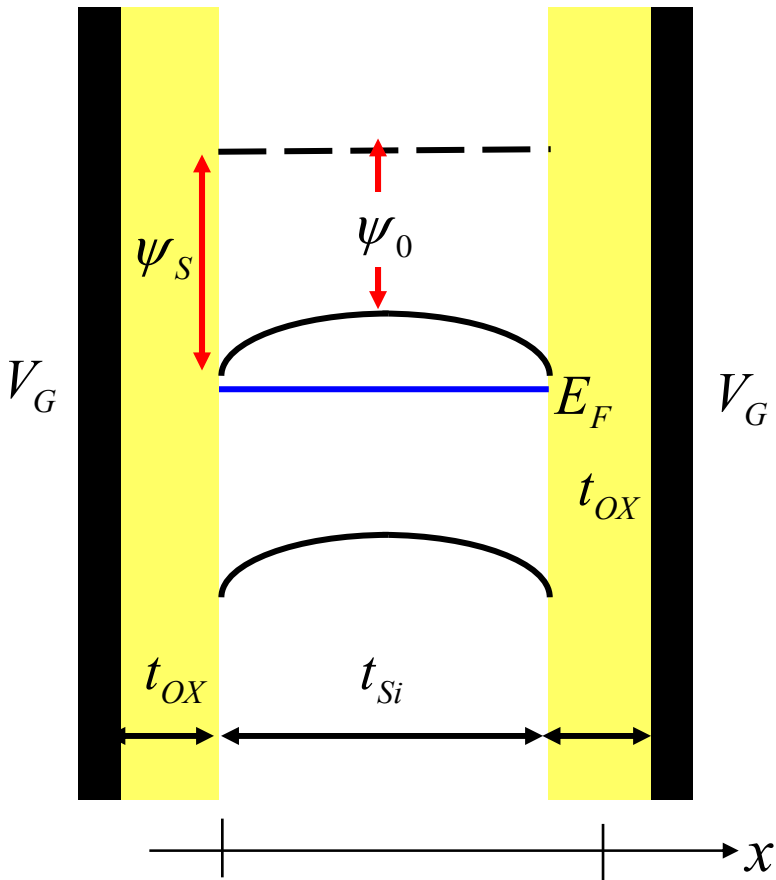
-volume inversion

3) strong inversion:

-strong band bending may develop

-volume inversion may be lost

'exact' UTB electrostatics



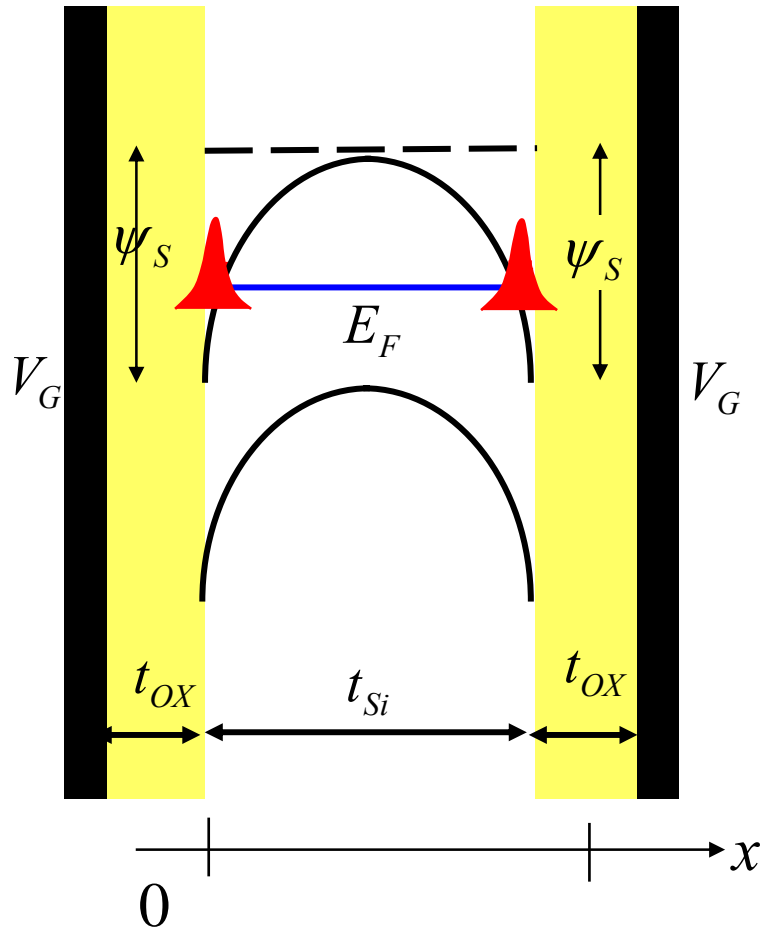
$$\frac{d^2 \psi(x)}{dx^2} = -\frac{\rho(x)}{\epsilon_{Si}} = \frac{qn_i}{\epsilon_{Si}} e^{q\psi(x)/k_B T}$$

can solve exactly, see:

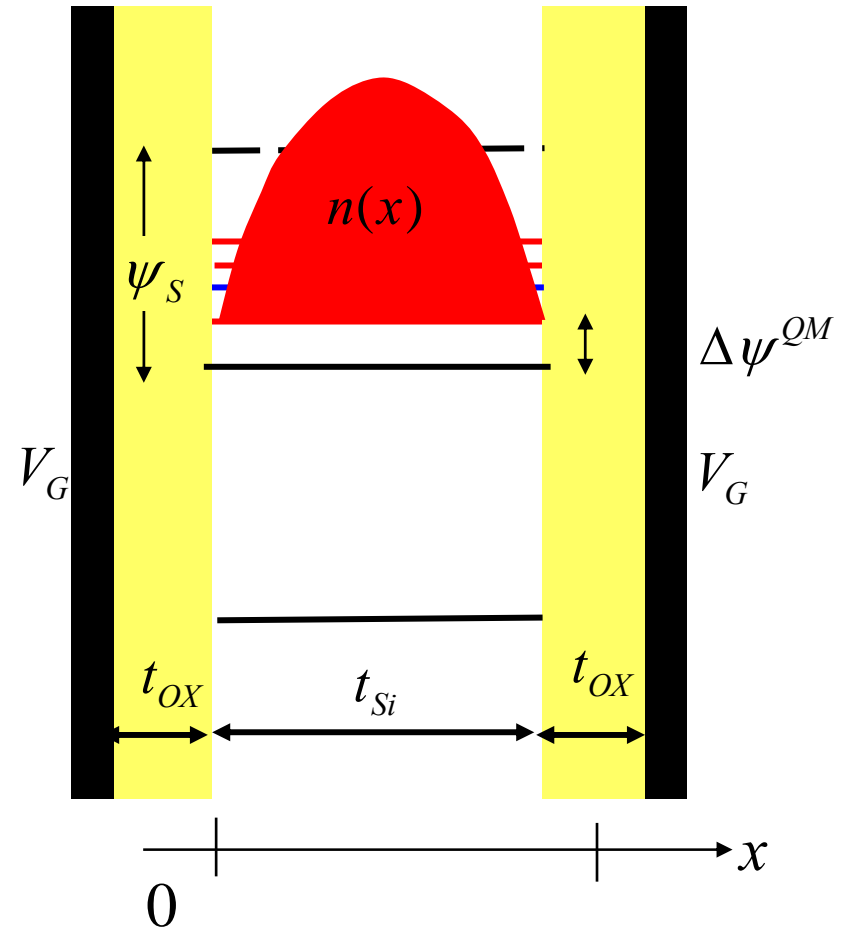
Y. Taur, "Analytic Solutions of Charge and Capacitance in Symmetric and Asymmetric Double-Gate MOSFETs, *IEEE Trans. Electron Dev.*, **48**, 2861-2869, 2001

quantum confinement

FD (thick)



FD (UTB)



numerical (Schred) simulation

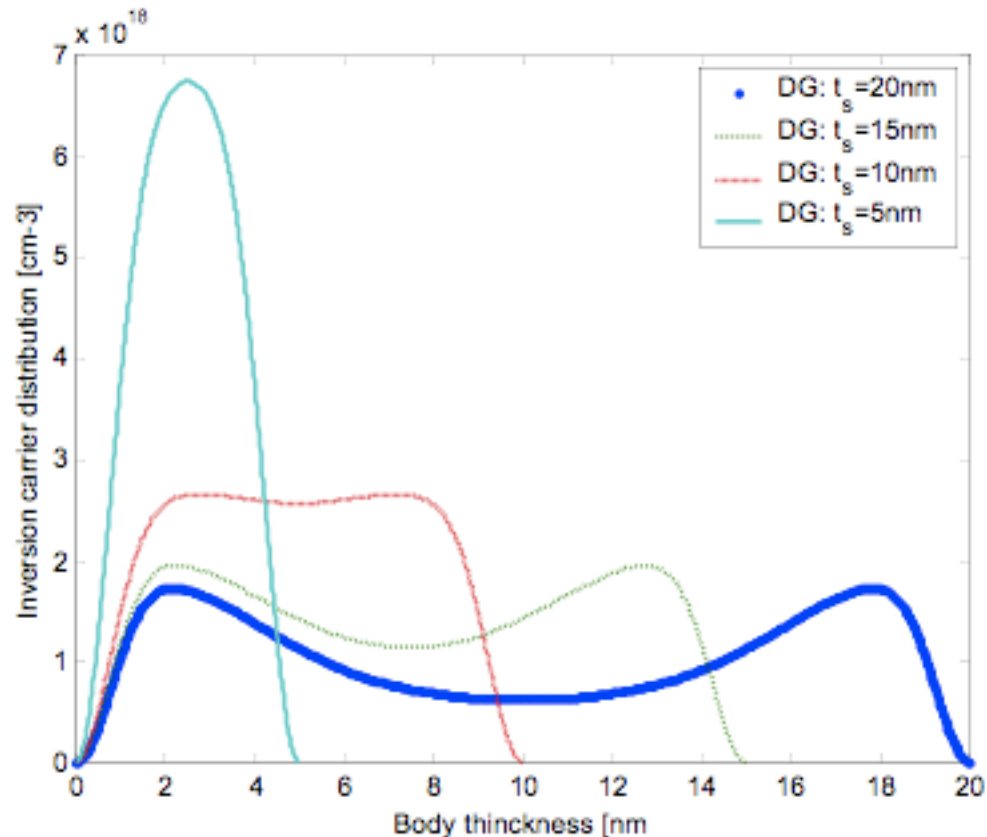


Fig. 20. Inversion carrier distribution inside the DGMOSC, for various body thickness, with $t_{ox}=10\text{nm}$, $N_d=1.E17\text{cm}^{-3}$, $V_G = 0.5\text{v}$.

numerical (Schred) simulation

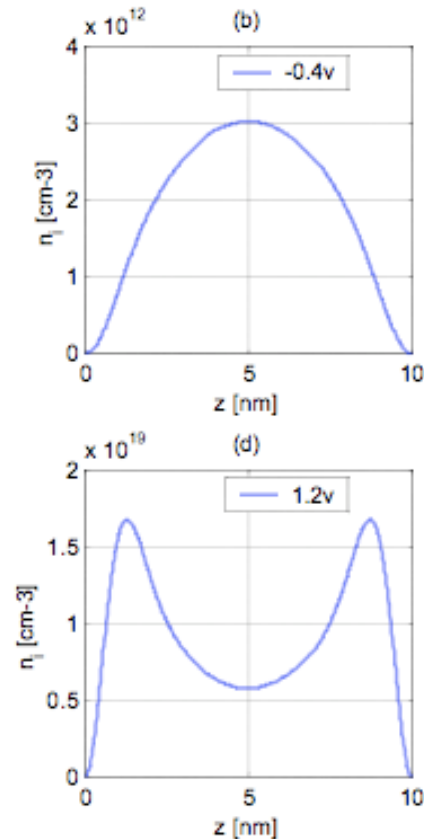


Fig. 22. Quantum calculation, $t_{\text{ox}}=5\text{nm}$, $t_{\text{si}}=10\text{nm}$, $N_A=1.e17\text{cm}^{-3}$. (a) variation of centroid with gate voltage, rest three are electron distribution inside silicon film at gate voltage: (b) -0.4v , (c) 0.1v , (d) 1.2v .

quantum effects...

- 1) important when only a few subbands are occupied
ultra-ultra-thin body (5 nm or less)
- 2) increase V_T
- 3) lower C_S
- 4) increase ΔV_T because of body thickness variations
- 5) lower mobility because of increased surface roughness scattering

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SOI summary

1. SOI offers several advantages:
 - no latch-up
 - radiation hard
 - lower junction capacitance
 - good electrostatics (scaling, SS)
 - high drive current (DG)
2. But there are some trade-offs:
 - a more complex process
 - floating body effects
 - thermal issues